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Shirley

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[54] **PROCESS LIQUID DISPENSE METHOD AND APPARATUS**

[75] Inventor: **Paul Shirley**, Meridian, Id.

[73] Assignee: **Micron Technology, Inc.**, Boise, Id.

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[52] **U.S. Cl.** **427/240**; 427/385.5; 437/231

[58] **Field of Search** 427/240, 385.5; 437/231

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Primary Examiner—Janyce Bell
Attorney, Agent, or Firm—Kirkpatrick & Lockhart LLP

[57] **ABSTRACT**

Methods of dispensing process liquid to provide a uniform layer of the liquid on a surface are disclosed in accordance with the present invention. The methods include dispensing a process liquid on the surface and rotating the surface at a first speed to distribute an effective amount of the process liquid to substantially wet the surface. The method further includes rotating the surface at a second speed to distribute an effective amount of the process liquid to produce a layer of the process liquid on the surface. In a preferred embodiment or dispensing photoresist onto the surface of a semiconductor wafer, the method includes rotating the wafer at the first speed prior to dispensing the photoresist onto the surface. The preferred method further includes decelerating the wafer from the first to the second speed during the dispensing of the photoresist and terminating the dispensing process after the second speed is reached.

24 Claims, 2 Drawing Sheets